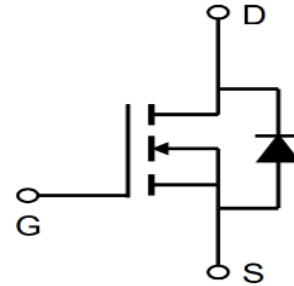




### Description

These N-Channel enhancement mode power field effect transistors are using shielded gate trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.



### General Features

$V_{DS} = 150V$   $I_D = 240A$

$R_{DS(ON)} < 5.8m\Omega$  @  $V_{GS}=10V$  (Type: 4.8m $\Omega$ )

### Application

DC/DC Converter

LED Backlighting

Power Management Switches

TO-220



TO-263



### Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	150	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	240	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	185	A
IDM	Pulsed Drain Current	720	A
EAS	Single Pulse Avalanche Energy	1764	mJ
IAS	Avalanche Current	64	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	326	W
TSTG	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient	0.46	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case	62	°C/W



### Electrical Characteristics (T<sub>c</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	150	165		V
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> =140V, V <sub>GS</sub> =0V			1	μA
IGSS	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA
VGS(th)	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	2.9	4.0	V
GFS	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =15A		33		S
RDS(ON)	Drain-Source On-State Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A		4.0	4.8	mΩ
Ciss	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz		4200		pF
Coss	Output Capacitance			2867		pF
Crss	Reverse Transfer Capacitance			215		pF
td(on)	Turn-on Delay Time	V <sub>GS</sub> =10V, V <sub>DS</sub> =75V, RL=1.07Ω, RGEN=3Ω		18		nS
tr	Turn-on Rise Time			22		nS
td(off)	Turn-Off Delay Time			35		nS
tr	Turn-Off Fall Time			10		nS
Qg	Total Gate Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =75V, I <sub>D</sub> =70A		65		nC
Qgs	Gate-Source Charge			20		nC
Qgd	Gate-Drain Charge			19		nC
ISD	Source-Drain Current (Body Diode)				240	A
VSD	Forward on Voltage <sup>(Note 3)</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =20A			1.2	V
trr	Reverse Recovery Time	I <sub>F</sub> =20A, dI/dt=500A/μs		101		ns
Qrr	Reverse Recovery Charge	I <sub>F</sub> =20A, dI/dt=500A/μs		1,240		nC

#### Notes:

- 1、 The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width ≤ 300μs , duty cycle ≤ 2%
- 3、 The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=50V, V<sub>GS</sub>=10V, L=0.5mH, I<sub>AS</sub>=64A
- 4、 The power dissipation is limited by 150°C junction temperature
- 5、 The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.



### Typical Characteristics

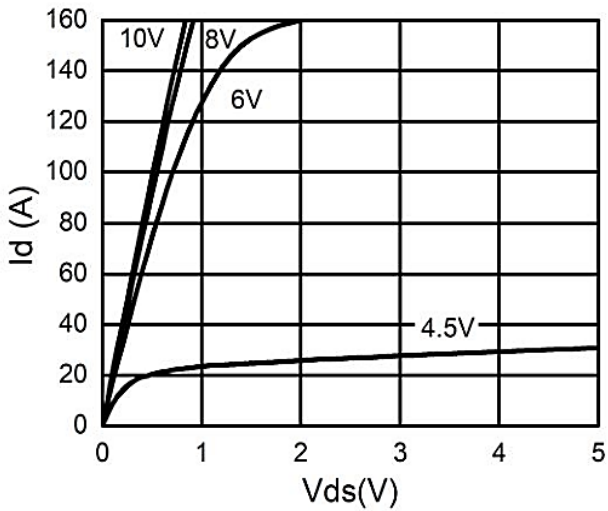


Figure 1. Output Characteristics

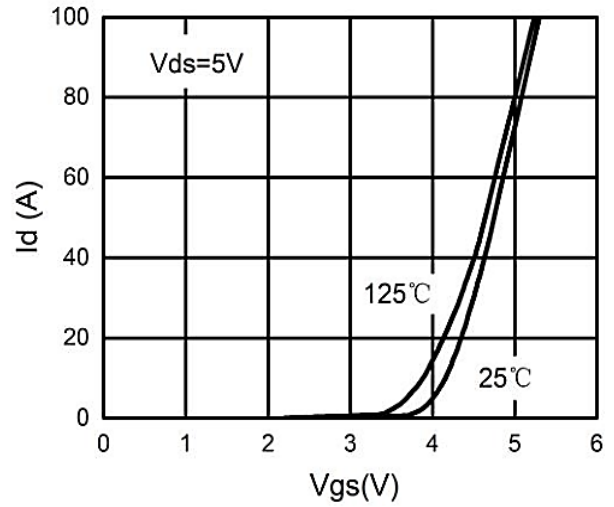


Figure 2. Transfer Characteristics

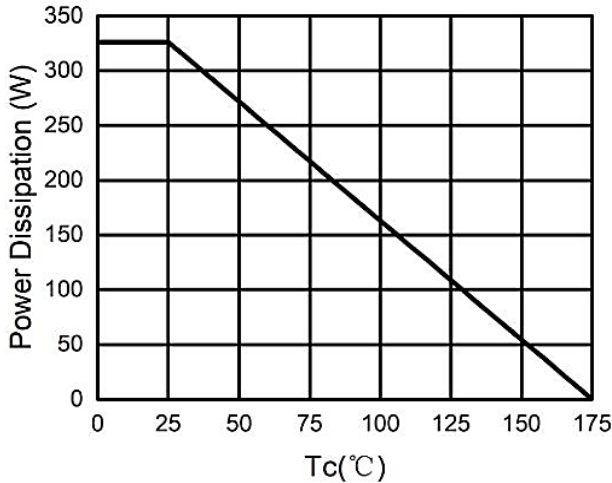


Figure 3. Power Dissipation

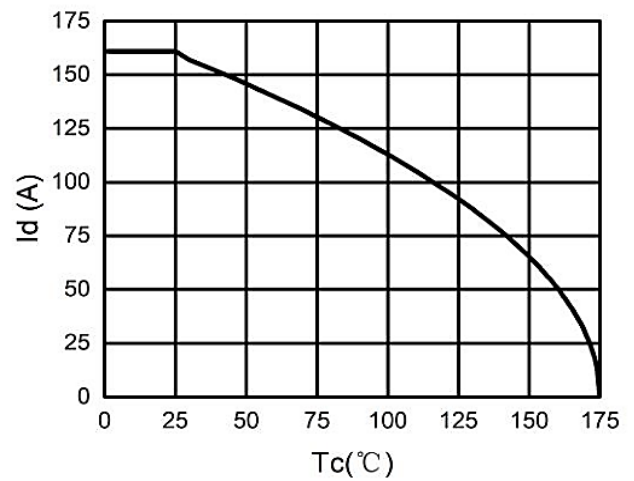


Figure 4. Drain Current

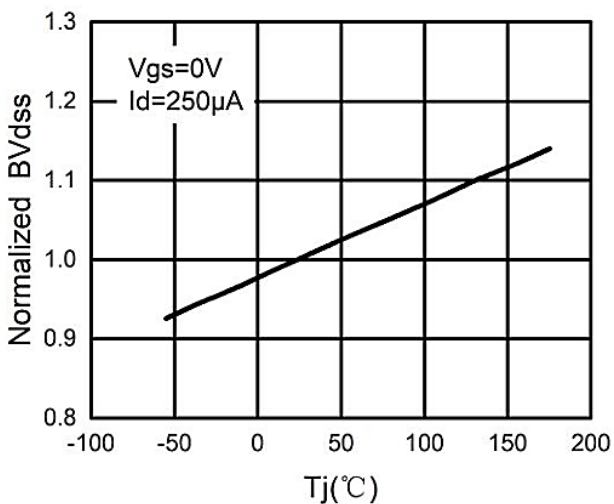


Figure 5.  $BV_{dss}$  vs Junction Temperature

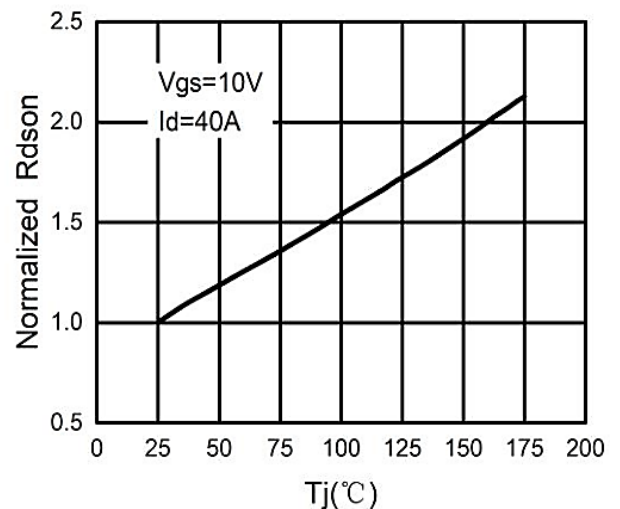


Figure 6.  $R_{ds(on)}$  vs Junction Temperature

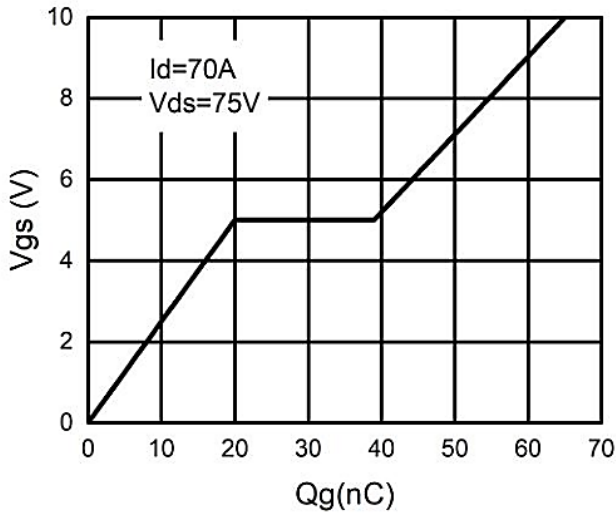


Figure 7. Gate Charge Waveforms

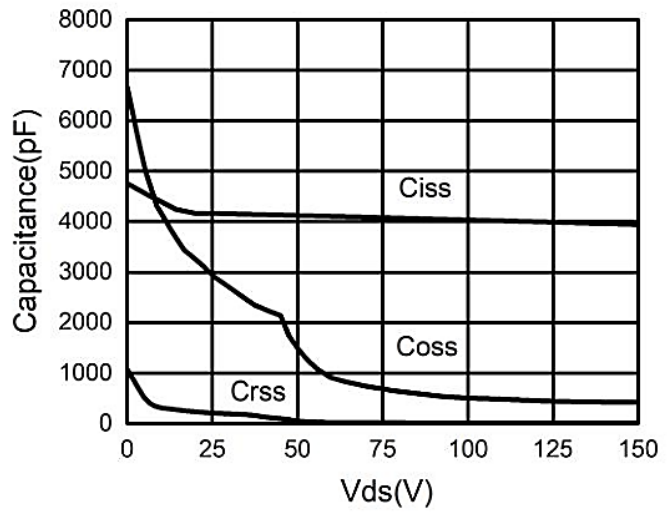


Figure 8. Capacitance

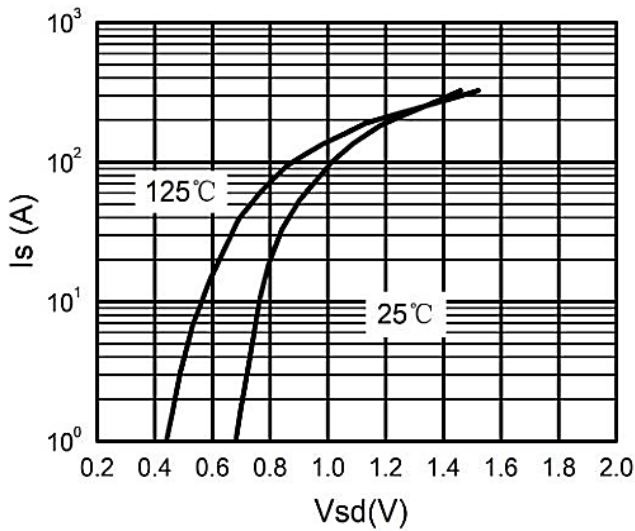


Figure 9. Body-Diode Characteristics

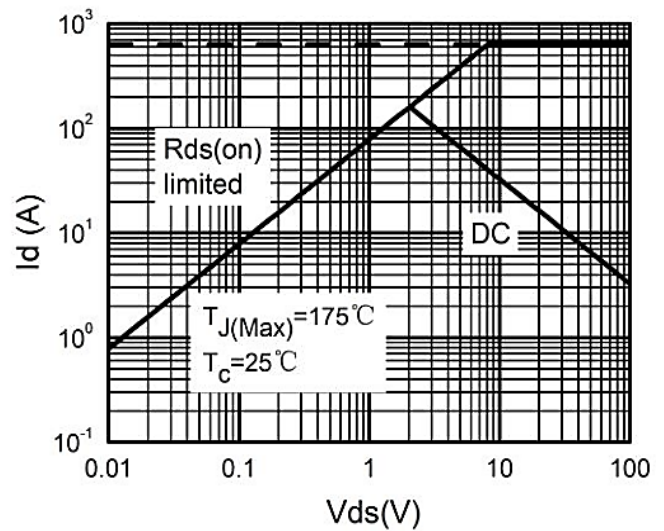


Figure 10. Maximum Safe Operating Area

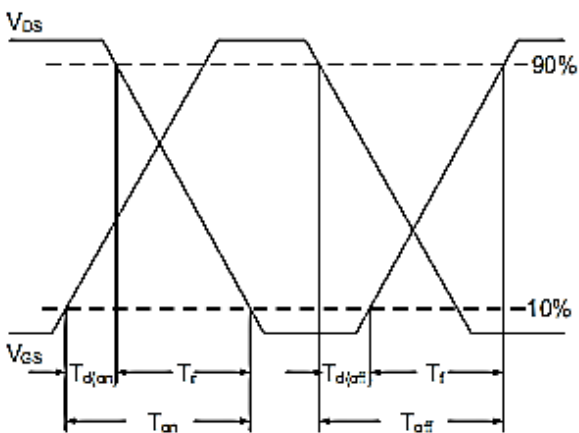


Figure 11. Switching Time Waveform

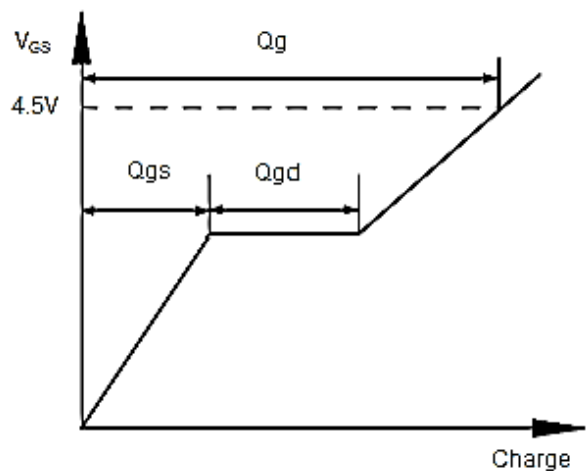
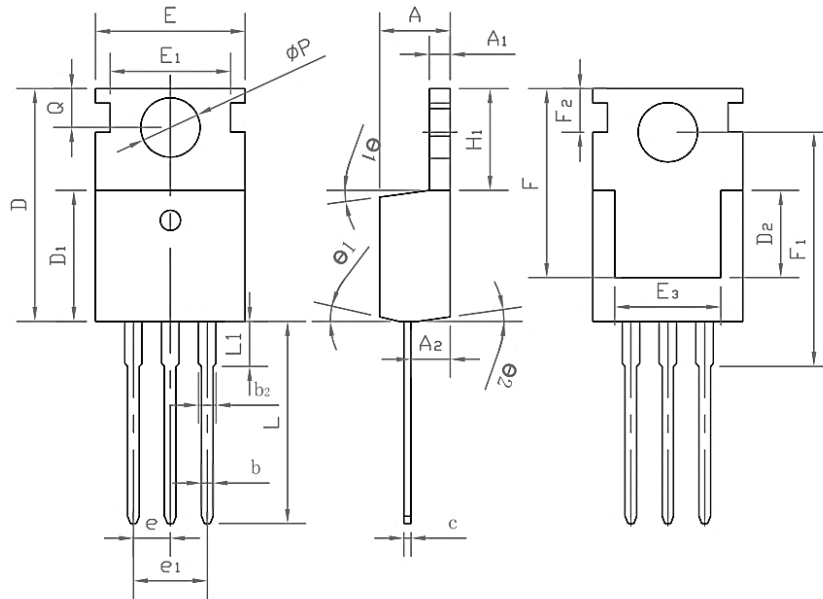


Figure 12. Gate Charge Waveform



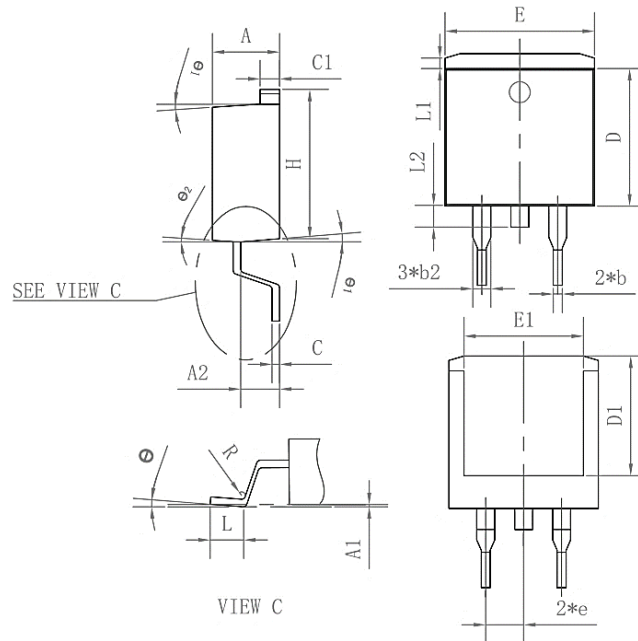
### Package Mechanical Data-TO-220-3L-SLK



Symbol	Common		
	mm		
	Mim	Nom	Max
A	4.27	4.57	4.87
A1	1.15	1.30	1.45
A2	2.10	2.40	2.70
b	0.70	0.80	1.00
b2	1.17	1.27	1.50
D	0.40	0.50	0.65
D1	8.80	9.10	9.40
D2	5.70	6.70	7.00
E	9.70	10.00	10.30
E1	-	8.70	-
E2	9.63	10.00	10.35
E3	7.00	8.00	8.40
e		0.37	
e1		0.10	
H1	6.00	6.50	6.85
L	12.75	13.50	13.90
L1	-	3.10	3.40
Φp	3.45	3.60	3.75
Q	2.60	2.80	3.00
θ1	4°	7°	10°
θ2	0°	3°	6°
F	13.30	13.50	13.70
F1	15.50	15.90	16.30
F2	2.80	3.00	3.20



### Package Mechanical Data-TO-263-3L-SLK



Symbol	Common		
	mm		
	Mim	Nom	Max
A	4.35	4.47	4.60
A1	0.09	0.10	0.11
A2	2.30	2.40	2.70
b	0.70	0.80	1.00
b2	1.25	1.36	1.50
C	0.45	0.50	0.65
C1	1.29	1.30	9.40
D	9.10	9.20	9.30
D1	7.90	8.00	8.10
E	9.85	10.00	10.20
E1	7.90	8.00	8.10
H	15.30	15.50	15.70
e	-	2.54	-
L	2.34	2.54	2.74
L1	1.00	1.10	1.20
L2	1.30	1.40	1.50
R	0.24	0.25	0.26
θ	0°	4°	8°
θ1	4°	7°	10°
θ2	0°	3°	6°



### Disclaimer

Brunei has made reasonable commercial efforts to ensure that the information given in this datasheet is correct. However, it must clearly be understood that such information is for guidance only and does not constitute any representation or form part of any offer or contract.

For documents and material available from this datasheet, Brunei does not warrant or assume any legal liability or responsibility for the accuracy, completeness, or usefulness of any information, product, technology or process disclosed hereunder.

Brunei reserves the rights to at its own discretion to make any changes or improvements to this datasheet. Unless said datasheet is incorporated into the formal contract, any customer should not rely on the information as any specification or product parameters duly committed by Brunei. Customers are hereby advised to verify that the information contained herein is current and complete before the entering of any contract or acknowledgement of any purchase order. Accordingly, all products specified hereunder shall be sold subject to Brunei's terms and conditions supplied at the time of order acknowledgement. Except where agreed upon by contractual agreement, testing of all parameters of each product is not necessarily performed.

Brunei does not warrant or convey any license either expressed or implied under its patent rights, nor the rights of others. Reproduction of information contained herein shall be only permissible if such reproduction is without any modification or alteration. Reproduction of this information with any alteration is an unfair and deceptive business practice. Brunei is not responsible or liable for such altered documentation.

Resale of Brunei's products with statements different from or beyond the parameters stated by Brunei for that product or service voids all express or implied warranties for the associated Brunei's product or service and is unfair and deceptive business practice. Brunei is not responsible or liable for any such statements.

Brunei's products are not authorized for use as critical components in life support devices or systems without the express written approval of Brunei. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.